

FORM PTO-1449 (Modified) MAY 07 2001 U.S. DEPARTMENT OF COMMERCE PATENT & TRADEMARK OFFICE (37 CFR 1.98(b))	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		POCKET NO. FORM 2132 (P129)	APPLICATION NO. 09/819,181
	INFORMATION DISCLOSURE STATEMENT BY APPLICANT			
	(Use several sheets if necessary)		APPLICANT Charles A. MILLER	FILING DATE March 27, 2001

U.S. PATENT DOCUMENTS

EXAM INIT	PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

EXAM INIT	DOCUMENT NUMBER	PUBL. DATE	COUNTRY OR PAT. OFFICE	CLASS	SUB CLASS	TRANS.	
						Y	N

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

cc	Gregus, Jeffrey A., Maureen Y. Lau, Yinon Degani and King L. Tai, "Chip-Scale Modules for High-Level Integration in the 21st Century," <u>BELL LABS TECHNICAL JOURNAL</u> , July-September 1998, pages 116-124
I	Mehra, Amit, Zin Zhang, Arturo A. Ayón, Ian A. Waitz, Martin A. Schmidt, "Through-wafer Electrical Interconnect for Multilevel Microelectromechanical System Devices," <u>J. VAC. SCI. TECHNOL. B 18(5)</u> , Sep/Oct 2000, pages 2583-2589
I	"Through-Wafer Electrical Interconnects Compatible With Standard Semiconductor Processing," <u>mhtml:file://C:\TEMP\Eugene Chow hlton head.mht</u> , September 25, 2000
I	Murphy, Tom, "Tru-Si Technologies Makes Wafer Stacking a Possibility," <u>ELECTRONIC NEWS (1991)</u> , December 6, 1999
I	"2D Microcantilever Arrays with Through-Wafer Interconnects," <u>http://www.stanford.edu/~emc/2dpicts.html</u> , December 14, 2000
cc	"Employment of the Deep Plasma Silicon Etching for the Production of New Microfluidic Components," <u>http://222.tu-dresden.de/eti/m/english/research/hlt/ihm_eng/fo_pro_e/fra_e012.html</u> , December 15, 2000
cc	"Advanced Silicon Etch (ASE)", <u>http://www.stsystems.com/ase.html</u> , January 15, 2001

EXAMINER <i>cc</i>	DATE CONSIDERED <i>2/12/02</i>
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EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.